ABSTRACT

MOISTURE RESISTANT INTEGRATED CIRCUIT LEADFRAME PACKAGE

A leadframe for a semiconductor die includes signal leads, ground leads, and a die support holder for supporting the semiconductor die. The die support holder has opposite surfaces and side edges therebetween. The opposite die support holder surfaces are smaller in transverse extent than the semiconductor die for supporting the die on one of the opposite die support holder surfaces such that the die extends beyond the side edges of the die support holder. (Fig. 1)